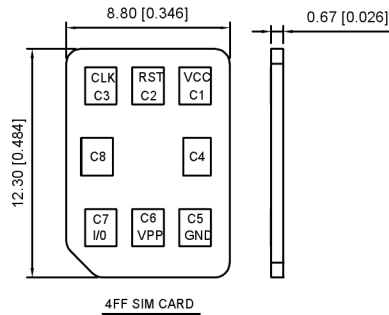
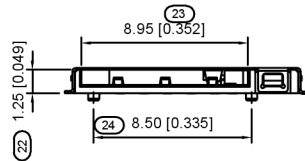


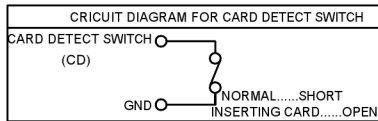
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



NOTES:

- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
TERMINAL:COPPER ALLOY
SHELL:SUS
- PLATING:
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:50m Ω MAX
3.4 Insulation Resistance:1000M Ω MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:260±0/-5 °C, 30±10s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition:Temperature-40 °C~+85 °C;
Humidity 80% R.H MAX

PAD
 KEEP OUT AREA



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

广东星坤科技股份有限公司

日期

文件工程章

REV	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES

DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	SIM CARD CONN
CHKD	UNIT: mm/in	PART NO.:
APPD	SIZE: A4	DWG NO.:
XKB INDUSTRIAL PRECISION CO.,LIMITED		XKNANO-113
WEIGHT	SHEET	REVISIOI
	1/1	A0